(12) INTERNATIONAL APPLICATION PUBLISHED UNDER THE PATENT COOPERATION TREATY (PCT)

(19) World Intellectual Property Organization
International Bureau

(43) International Publication Date
9 December 2010 (09.12.2010)

PCT

(10) International Publication Number
WO 2010/141652 A2

(51) International Patent Classification:
H01L 21/304 (2006.01)

(21) International Application Number:
PCT/US2010/037158

(22) International Filing Date:
3 June 2010 (03.06.2010)

(25) Filing Language: English

(26) Publication Language: English

(30) Priority Data:
12/455,631 4 June 2009 (04.06.2009) US

(71) Applicant *(for all designated States except US)*: **CABOT MICROELECTRONICS CORPORATION** [US/US]; Legal Department, 870 N. Commons Drive, Aurora, Illinois 60504 (US).

(72) Inventors; and

(75) Inventors/Applicants *(for US only)*: **PALANISAMY CHINNATHAMBI, Selvaraj** [IN/SG]; c/o Legal Department, Cabot Microelectronics Corporation, 870 North Commons Drive, Aurora, Illinois 60504 (US). **SIRIWARDANE, Haresh** [US/SG]; c/o Legal Department, Cabot Microelectronics Corporation, 870 North Commons Drive, Aurora, Illinois 60504 (US).

(74) Agents: **WESEMAN, Steven** et al.; Cabot Microelectronics Corp., 870 N. Commons Drive, Aurora, Illinois 60504 (US).

(81) Designated States *(unless otherwise indicated, for every kind of national protection available)*: AE, AG, AL, AM, AO, AT, AU, AZ, BA, BB, BG, BH, BR, BW, BY, BZ, CA, CH, CL, CN, CO, CR, CU, CZ, DE, DK, DM, DO, DZ, EC, EE, EG, ES, FI, GB, GD, GE, GH, GM, GT, HN, HR, HU, ID, IL, IN, IS, JP, KE, KG, KM, KN, KP, KR, KZ, LA, LC, LK, LR, LS, LT, LU, LY, MA, MD, ME, MG, MK, MN, MW, MX, MY, MZ, NA, NG, NI, NO, NZ, OM, PE, PG, PH, PL, PT, RO, RS, RU, SC, SD, SE, SG, SK, SL, SM, ST, SV, SY, TH, TJ, TM, TN, TR, TT, TZ, UA, UG, US, UZ, VC, VN, ZA, ZM, ZW.

(84) Designated States *(unless otherwise indicated, for every kind of regional protection available)*: ARIPO (BW, GH, GM, KE, LR, LS, MW, MZ, NA, SD, SL, SZ, TZ, UG, ZM, ZW), Eurasian (AM, AZ, BY, KG, KZ, MD, RU, TJ, TM), European (AL, AT, BE, BG, CH, CY, CZ, DE, DK, EE, ES, FI, FR, GB, GR, HR, HU, IE, IS, IT, LT, LU, LV, MC, MK, MT, NL, NO, PL, PT, RO, SE, SI, SK, SM, TR), OAPI (BF, BJ, CF, CG, CI, CM, GA, GN, GQ, GW, ML, MR, NE, SN, TD, TG).

Declarations under Rule 4.17:

— *as to applicant's entitlement to apply for and be granted a patent (Rule 4.17(ii))*

— *as to the applicant's entitlement to claim the priority of the earlier application (Rule 4.17(iii))*

Published:

— *without international search report and to be republished upon receipt of that report (Rule 48.2(g))*

WO 2010/141652 A2

(54) **Title**: POLISHING COMPOSITION FOR NICKEL-PHOSPHOROUS MEMORY DISKS

(57) **Abstract**: The invention provides a chemical-mechanical polishing composition comprising alpha alumina, fumed alumina, silica, an oxidizing agent that oxidizes nickel phosphorous, a complexing agent, and water. The invention also provides a method of chemically-mechanically polishing a substrate comprising contacting a substrate with a polishing pad and the chemical-mechanical polishing composition, moving the polishing pad and the polishing composition relative to the substrate, and abrading at least a portion of the substrate to polish the substrate.